Device Material Content

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Package: 554 caBGA
Total Device Weight 1.79 Grams

Package Code: BG554
Products: FE5

Assembly: ASEM
Size (mm): 23 x 23
Lead pitch (mm): 0.8
MSL: 3
Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.49%	0.0267						Die size: 6.55 x 7.04mm
			1.49%	0.0267	Silicon chip	7440-21-3	100.00%	
Mold Compound	44.60%	0.7979						Mold Compound: Sumitomo G750SE (ULA)
			3.12%	0.0559	Epoxy Resin	-	7.00%	
			2.23%	0.0399	Phenol Novolac	9003-35-4	5.00%	
			2.23%	0.0399	Metal Hydroxide	-	5.00%	
			0.22%	0.0040	Carbon Black	1333-86-4	0.50%	
			36.80%	0.6583	Silica Fused	60676-86-0	82.50%	
D/A Epoxy	0.22%	0.0039						Die attach epoxy: Henkel (Ablebond) 2100A
			0.18%	0.00315	Silver	7440-22-4	80.00%	
			0.04%	0.00079	Esters & resins	-	20.00%	
Wire	0.18%	0.0032						0.8 mil diameter; 1 wire per solder ball
			0.177%	0.00317	Copper	7440-50-8	98.50%	
			0.003%	0.00005	Palladium	7440-05-3	1.50%	
Solder Balls	7.72%	0.1381						SAC305
			7.45%	0.1333	Tin (Sn)	7440-31-5	96.50%	
			0.23%	0.0041	Silver (Ag)	7440-22-4	3.00%	
			0.04%	0.0007	Copper (Cu)	7440-50-8	0.50%	
Substrate	29.76%	0.5325						BT Resin CCL-HL832NX-A
			9.52%	0.1704	BT Resins	-	32.00%	
			20.24%	0.3621	Glass fiber	65997-17-3	68.00%	
Foil	11.12%	0.1990						
			9.41%	0.1683	Copper	7440-50-8	84.56%	
			1.63%	0.0292	Nickel	7440-02-0	14.70%	
			0.08%	0.0015	Gold	7440-57-5	0.74%	
Solder Mask	4.90%	0.0877						Solder mask PSR4000 AUS 308
			2.76%	0.0493	Quartz	14808-60-7	56.20%	
			0.78%	0.0140	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			1.08%	0.0193	Barium Sulfate	7727-43-7	22.00%	
			0.15%	0.0026	Talc (containing no asbestiform fibers)	14807-96-6	3.00%	
			0.14%	0.0025	Trade secret ingredients	-	2.80%	

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Br/Cl/Sb
Pb lead-free
RoHS

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